

## **Abstract Of The Invention**

A molded mount of non-crystalline polymer material is configured to have a channel for retaining a silicon chip having a plurality of juxtaposed V-groove formed in a top surface between right and left side portions, thereof, a recessed area being provided in the channel behind the chip for accommodating fiber buffer coating, and a notch being formed in a top portion of the mount between the channel and one side portion thereof, for retaining strengthening fibers of an optical fiber cable, with the V-groove being configured to receive individual optical fibers therein respectively. Two such molded mounts with silicon chips are securely sandwiched together with V-groove of the chips opposing one another to retain optical fibers therebetween.